



<b>Session Title:</b>	<b>[WeA2] Advanced Cu and Mo CMP</b>
<b>Session Date:</b>	<b>November 13 (Wed.), 2024</b>
<b>Session Time:</b>	<b>14:10-15:45</b>
<b>Session Room:</b>	<b>Room A (Capri Room, 2F, Paradise Hotel Busan)</b>
<b>Session Chair:</b>	<b>Prof. Ho Jun Kim (Hanyang Univ., Korea)</b>

**[WeA2-1] [Invited] 14:10-14:40**

### **Predicting Corrosion Inhibition Efficiency based on Charge Transfer Factor**

Ganghyeok Kim, Ilhwa Hong, Donggeun Park, Wangil Song, Seokju Hong, Dongwon Kim, and Kangchun Lee (Kyonggi Univ., Korea)

**[WeA2-2] [Invited] 14:40-15:05**

### **Amorphous Cabon Layer CMP: Material Properties and Solution**

Jea-Gun Park (Hanyang Univ., Korea)

**[WeA2-3] 15:05-15:25**

### **Study on the Effect of Corrosion Inhibitors during Chemical Mechanical Planarization of Molybdenum**

Daecheon Yang, Soekjoo Kim (Soulbrain Co., Ltd., Korea), Sangkyun Kim, Inkwon Kim, and Gayoung Kim (Samsung Electronics Co., Ltd., Korea)

**[WeA2-4] 15:25-15:45**

### **Advanced Additives for Enhanced Removal Rate and Defect Mitigation in Copper CMP Slurries**

Junhyuk Kim and Seokjoo Kim (Soulbrain Co., Ltd., Korea)